FAIRCHILD
SEMICONDUCTOR ™

March 1998
Revised August 2001

74VCX16601
Low Voltage 18-Bit Universal Bus Transceivers with 3.6V Tolerant Inputs and Outputs

General Description

The VCX16601 is an 18-bit universal bus transceiver which combines D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is HIGH. When LEAB is LOW, the A data is latched if CLKAB is held at a HIGH-to-LOW logic level. If LEAB is LOW, the A bus data is stored in the latch/flip-flop on the LOW-to-HIGH transition of CLKAB. When $\overline{OEAB}$ is LOW, the outputs are active. When $\overline{OEAB}$ is HIGH, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses $\overline{OEBA}$, LEBA, CLKBA and $\overline{CLKENBA}$.

The VCX16601 is designed for low voltage (1.65V to 3.6V) V_{CC} applications with I/O capability up to 3.6V.

The VCX16601 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining low CMOS power dissipation.

Features

■ 1.65V–3.6V V_{CC} supply operation

■ 3.6V tolerant inputs and outputs

■ t_{PD} (A to B, B to A)

   2.9 ns max for 3.0V to 3.6V V_{CC}

   3.5 ns max for 2.3V to 2.7V V_{CC}

   7.0 ns max for 1.65V 1.95V V_{CC}

■ Power-down high impedance inputs and outputs

■ Supports live insertion/withdrawal (Note 1)

■ Static Drive (I_{OH}/I_{OL})

   ±24 mA @ 3.0V V_{CC}

   ±18 mA @ 2.3V V_{CC}

   ±6 mA @ 1.65V V_{CC}

■ Uses patented noise/EMI reduction circuitry

■ Latchup performance exceeds 300 mA

■ ESD performance:

   Human body model > 2000V

   Machine model >200V

■ Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

Note 1: To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pull-up resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.
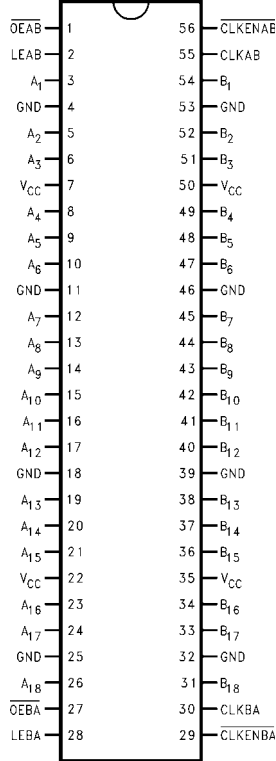
Ordering Code:

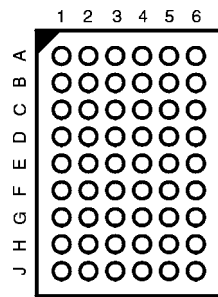| Order Number	Package Number	Package Description
74VCX16601GX (Note 2)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [TAPE and REEL]
74VCX16601MTD (Note 3)	MTD56	56-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 2: BGA package available in Tape and Reel only.

Note 3: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

74VCX16601

Connection Diagrams

Pin Assignment for TSSOP

$\overline{OEAB}$	1		56	$\overline{CLKENAB}$
LEAB	2		55	CLKAB
A_1	3		54	B_1
GND	4		53	GND
A_2	5		52	B_2
A_3	6		51	B_3
V_{CC}	7		50	V_{CC}
A_4	8		49	B_4
A_5	9		48	B_5
A_6	10		47	B_6
GND	11		46	GND
A_7	12		45	B_7
A_8	13		44	B_8
A_9	14		43	B_9
A_{10}	15		42	B_{10}
A_{11}	16		41	B_{11}
A_{12}	17		40	B_{12}
GND	18		39	GND
A_{13}	19		38	B_{13}
A_{14}	20		37	B_{14}
A_{15}	21		36	B_{15}
V_{CC}	22		35	V_{CC}
A_{16}	23		34	B_{16}
A_{17}	24		33	B_{17}
GND	25		32	GND
A_{18}	26		31	B_{18}
$\overline{OEBA}$	27		30	CLKBA
LEBA	28		29	$\overline{CLKENBA}$

Pin Assignment for FBGA

(Top Thru View)

Pin Descriptions

Pin Names	Description
$\overline{OEAB}$, $\overline{OEBA}$	Output Enable Inputs (Active LOW)
LEAB, LEBA	Latch Enable Inputs
CLKAB, CLKBA	Clock Inputs
$\overline{CLKENAB}$, $\overline{CLKENBA}$	Clock Enable Inputs
A_1–A_{18}	Side A Inputs or 3-STATE Outputs
B_1–B_{18}	Side B Inputs or 3-STATE Outputs

FBGA Pin Assignments

	1	2	3	4	5	6
A	A_2	A_1	$\overline{OEAB}$	$\overline{CLKENAB}$	B_1	B_2
B	A_4	A_3	LEAB	CLKAB	B_3	B_4
C	A_6	A_5	V_{CC}	V_{CC}	B_5	B_6
D	A_8	A_7	GND	GND	B_7	B_8
E	A_{10}	A_9	GND	GND	B_9	B_{10}
F	A_{12}	A_{11}	GND	GND	B_{11}	B_{12}
G	A_{14}	A_{13}	V_{CC}	V_{CC}	B_{13}	B_{14}
H	A_{16}	A_{15}	$\overline{OEBA}$	CLKBA	B_{15}	B_{16}
J	A_{17}	A_{18}	LEBA	$\overline{CLKENBA}$	B_{18}	B_{17}

Truth Table

(Note 4)

Inputs					Outputs
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	A_n	B_n
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B_0 (Note 5)
H	L	L	X	X	B_0 (Note 5)
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B_0 (Note 5)
L	L	L	H	X	B_0 (Note 6)

H = HIGH Voltage Level
L = LOW Voltage Level
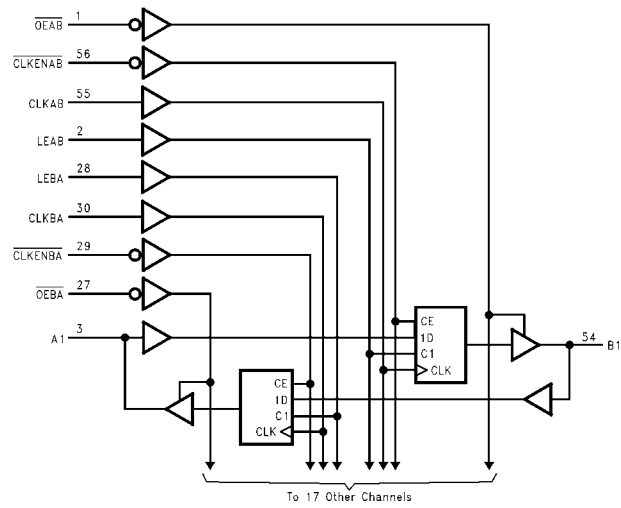X = Immaterial (HIGH or LOW, inputs may not float)
Z = High Impedance

Note 4: A-to-B data flow is shown; B-to-A flow is similar but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CLKENBA}$.

Note 5: Output level before the indicated steady-state input conditions were established.

Note 6: Output level before the indicated steady-state input conditions were established, provided that CLKAB was HIGH before LEAB went LOW.

Logic Diagram

$\overline{\text{OEAB}}$ 1

$\overline{\text{CLKENAB}}$ 56

CLKAB 55

LEAB 2

LEBA 28

CLKBA 30

$\overline{\text{CLKENBA}}$ 29

$\overline{\text{OEBA}}$ 27

A1 3

CE
1D
C1
CLK

CE
1D
C1
CLK

54 B1

To 17 Other Channels

Absolute Maximum Ratings(Note 7)

Supply Voltage (V_{CC})	−0.5V to +4.6V
DC Input Voltage (V_I)	−0.5V to +4.6V
Output Voltage (V_O)	
Outputs 3-Stated	−0.5V to +4.6V
Outputs Active (Note 8)	−0.5 to V_{CC} + 0.5V
DC Input Diode Current (I_{IK}) V_I < 0V	−50 mA
DC Output Diode Current (I_{OK})	
V_O < 0V	−50 mA
V_O > V_{CC}	+50 mA
DC Output Source/Sink Current	
(I_{OH}/I_{OL})	±50 mA
DC V_{CC} or Ground Current per	
Supply Pin (I_{CC} or Ground)	±100 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C

Recommended Operating Conditions (Note 9)

Power Supply	
Operating	1.65V to 3.6V
Data Retention Only	1.2V to 3.6V
Input Voltage	−0.3V to 3.6V
Output Voltage (V_O)	
Output in Active States	0V to V_{CC}
Output in 3-STATE	0.0V to 3.6V
Output Current in I_{OH}/I_{OL}	
V_{CC} = 3.0V to 3.6V	±24 mA
V_{CC} = 2.3V to 2.7V	±18 mA
V_{CC} = 1.65V to 2.3V	±6 mA
Free Air Operating Temperature (T_A)	−40°C to +85°C
Minimum Input Edge Rate ($\Delta t/\Delta V$)	
V_{IN} = 0.8V to 2.0V, V_{CC} = 3.0V	10 ns/V

Note 7: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The Recommended Operating Conditions tables will define the conditions for actual device operation.

Note 8: I_O Absolute Maximum Rating must be observed.

Note 9: Floating or unused pin (inputs or I/O's) must be held HIGH or LOW.

DC Electrical Characteristics (2.7V < V_{CC} ≤ 3.6V)

Symbol	Parameter	Conditions	V_{CC} (V)	Min	Max	Units
V_{IH}	HIGH Level Input Voltage		2.7 – 3.6	2.0		V
V_{IL}	LOW Level Input Voltage		2.7 – 3.6		0.8	V
V_{OH}	HIGH Level Output Voltage	I_{OH} = −100 µA	2.7 – 3.6	V_{CC} − 0.2		V
		I_{OH} = −12 mA	2.7	2.2		
		I_{OH} = −18 mA	3.0	2.4		
		I_{OH} = −24 mA	3.0	2.2		
V_{OL}	LOW Level Output Voltage	I_{OL} = 100 µA	2.7 – 3.6		0.2	V
		I_{OL} = 12 mA	2.7		0.4	
		I_{OL} = 18 mA	3.0		0.4	
		I_{OL} = 24 mA	3.0		0.55	
I_I	Input Leakage Current	0V ≤ V_I ≤ 3.6V	2.7 – 3.6		±5.0	µA
I_{OZ}	3-STATE Output Leakage	0V ≤ V_O ≤ 3.6V V_I = V_{IH} or V_{IL}	2.7 – 3.6		±10	µA
I_{OFF}	Power Off Leakage Current	0V ≤ (V_I, V_O) ≤ 3.6V	0		10	µA
I_{CC}	Quiescent Supply Current	V_I = V_{CC} or GND	2.7 – 3.6		20	µA
		V_{CC} ≤ (V_I, V_O) ≤ 3.6V (Note 10)	2.7 – 3.6		±20	
ΔI_{CC}	Increase in I_{CC} per Input	V_{IH} = V_{CC} − 0.6V	2.7 – 3.6		750	µA

Note 10: Outputs disabled or 3-STATE only.

DC Electrical Characteristics (2.3V ≤ V$_{CC}$ ≤ 2.7V)

Symbol	Parameter	Conditions	V$_{CC}$ (V)	Min	Max	Units
V$_{IH}$	HIGH Level Input Voltage		2.3 – 2.7	1.6		V
V$_{IL}$	LOW Level Input Voltage		2.3 – 2.7		0.7	V
V$_{OH}$	HIGH Level Output Voltage	I$_{OH}$ = −100 μA	2.3 – 2.7	V$_{CC}$ − 0.2		V
		I$_{OH}$ = −6 mA	2.3	2.0		
		I$_{OH}$ = −12 mA	2.3	1.8		
		I$_{OH}$ = −18 mA	2.3	1.7		
V$_{OL}$	LOW Level Output Voltage	I$_{OL}$ = 100 μA	2.3 – 2.7		0.2	V
		I$_{OL}$ = 12 mA	2.3		0.4	
		I$_{OL}$ = 18 mA	2.3		0.6	
I$_I$	Input Leakage Current	0 ≤ V$_I$ ≤ 3.6V	2.3 – 2.7		±5.0	μA
I$_{OZ}$	3-STATE Output Leakage	0 ≤ V$_O$ ≤ 3.6V V$_I$ = V$_{IH}$ or V$_{IL}$	2.3 – 2.7		±10	μA
I$_{OFF}$	Power Off Leakage Current	0 ≤ (V$_I$, V$_O$) ≤ 3.6V	0		10	μA
I$_{CC}$	Quiescent Supply Current	V$_I$ = V$_{CC}$ or GND	2.3 – 2.7		20	μA
		V$_{CC}$ ≤ (V$_I$, V$_O$) ≤ 3.6V (Note 11)	2.3 – 2.7		±20	

Note 11: Outputs disabled or 3-STATE only.

DC Electrical Characteristics (1.65V ≤ V$_{CC}$ < 2.3V)

Symbol	Parameter	Conditions	V$_{CC}$ (V)	Min	Max	Units
V$_{IH}$	HIGH Level Input Voltage		1.65 - 2.3	0.65 × V$_{CC}$		V
V$_{IL}$	LOW Level Input Voltage		1.65 - 2.3		0.35 × V$_{CC}$	V
V$_{OH}$	HIGH Level Output Voltage	I$_{OH}$ = −100 μA	1.65 - 2.3	V$_{CC}$ − 0.2		V
		I$_{OH}$ = −6 mA	1.65	1.25		
V$_{OL}$	LOW Level Output Voltage	I$_{OL}$ = 100 μA	1.65 - 2.3		0.2	V
		I$_{OL}$ = 6 mA	1.65		0.3	
I$_I$	Input Leakage Current	0 ≤ V$_I$ ≤ 3.6V	1.65 - 2.3		±5.0	μA
I$_{OZ}$	3-STATE Output Leakage	0 ≤ V$_O$ ≤ 3.6V V$_I$ = V$_{IH}$ or V$_{IL}$	1.65 - 2.3		±10	μA
I$_{OFF}$	Power Off Leakage Current	0 ≤ (V$_I$, V$_O$) ≤ 3.6V	0		10	μA
I$_{CC}$	Quiescent Supply Current	V$_I$ = V$_{CC}$ or GND	1.65 - 2.3		20	μA
		V$_{CC}$ ≤ (V$_I$, V$_O$) ≤ 3.6V (Note 12)	1.65 - 2.3		±20	

Note 12: Outputs disabled or 3-STATE only.

AC Electrical Characteristics (Note 13)

Symbol	Parameter	$T_A = -40°C$ to $+85°C$, $C_L = 30$ pF, $R_L = 500\Omega$						Units
		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 2.5 \pm 0.2V$		$V_{CC} = 1.8V \pm 0.15V$		
		Min	Max	Min	Max	Min	Max	
f_{MAX}	Maximum Clock Frequency	250		200		100		MHz
t_{PHL} t_{PLH}	Propagation Delay Bus to Bus	0.8	2.9	1.0	3.5	1.5	7.0	ns
t_{PHL} t_{PLH}	Propagation Delay Clock to Bus	0.8	3.5	1.0	4.4	1.5	8.8	ns
t_{PHL} t_{PLH}	Propagation Delay LE to Bus	0.8	3.5	1.0	4.4	1.5	8.8	ns
t_{PZL} t_{PZH}	Output Enable Time	0.8	3.8	1.0	4.9	1.5	9.8	ns
t_{PLZ} t_{PHZ}	Output Disable Time	0.8	3.7	1.0	4.2	1.5	7.6	ns
t_S	Setup Time	1.5		1.5		2.5		ns
t_H	Hold Time	1.0		1.0		1.0		ns
t_W	Pulse Width	1.5		1.5		4.0		ns
t_{OSHL} t_{OSLH}	Output to Output Skew (Note 14)		0.5		0.5		0.75	ns

Note 13: For $C_L = 50$pF, add approximately 300ps to the AC maximum specification.

Note 14: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = +25°C$ Typical	Units
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	$C_L = 30$ pF, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	1.8	0.25	
			2.5	0.6	V
			3.3	0.8	
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	$C_L = 30$ pF, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	1.8	−0.25	
			2.5	−0.6	V
			3.3	−0.8	
V_{OHV}	Quiet Output Dynamic Valley V_{OH}	$C_L = 30$ pF, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	1.8	1.5	
			2.5	1.9	V
			3.3	2.2	

Capacitance

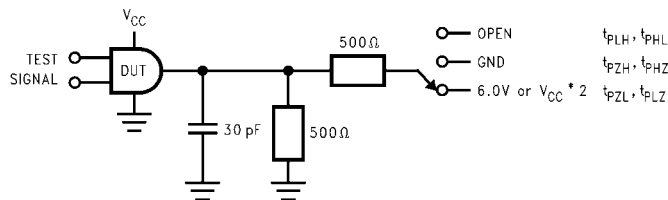| Symbol	Parameter	Conditions	$T_A = +25°C$	Units
C_{IN}	Input Capacitance	$V_I = 0V$ or V_{CC} $V_{CC} = 1.8V$, 2.5V, or 3.3V	6	pF
$C_{I/O}$	Output Capacitance	$V_I = 0V$ or V_{CC}, $V_{CC} = 1.8V$, 2.5V or 3.3V	7	pF
C_{PD}	Power Dissipation Capacitance	$V_I = 0V$ or V_{CC}, f = 10 MHz $V_{CC} = 1.8V$, 2.5V or 3.3V	20	pF

AC Loading and Waveforms

FIGURE 1. AC Test Circuit

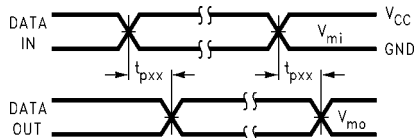| TEST	SWITCH
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$; V_{CC} x 2 at $V_{CC} = 2.5 \pm 0.2V$; $1.8V \pm 0.15V$
t_{PZH}, t_{PHZ}	GND

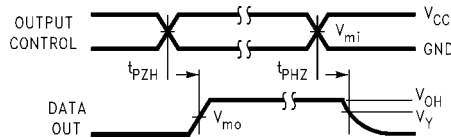**FIGURE 2. Waveform for Inverting and Non-inverting Functions**

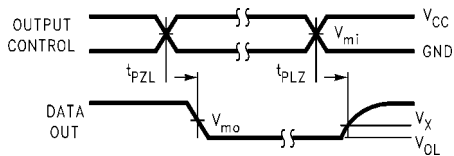**FIGURE 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic**
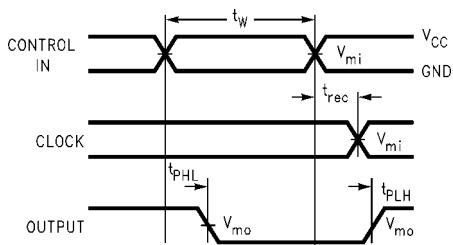

FIGURE 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

FIGURE 5. Propagation Delay, Pulse Width and t_{rec} Waveforms
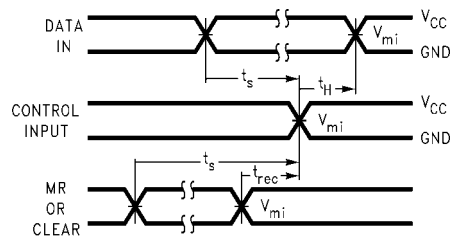
FIGURE 6. Setup Time, Hold Time and Recovery Time for Low Voltage Logic

Symbol	V_{CC}		
	3.3V $\pm$ 0.3V	**2.5V $\pm$ 0.2V**	**1.8V $\pm$ 0.15V**
V_{mi}	1.5V	$V_{CC}/2$	$V_{CC}/2$
V_{mo}	1.5V	$V_{CC}/2$	$V_{CC}/2$
V_X	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$	$V_{OL} + 0.15V$
V_Y	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$	$V_{OH} - 0.15V$

Physical Dimensions inches (millimeters) unless otherwise noted

⌒ 0.10 B

B ► 5.5

A

⌒ 0.10 A

8

PIN ONE

Top
View

4

0.4 0.8

(0.8)

(0.75)

A B C D E F G H J

6.4

0.8

1 2 3 4 5 6

Bottom
View

54X 0.5 +0.05 −0.05

⊕ | 0.15 Ⓜ | C | A | B
| 0.08 Ⓜ | C

// 0.15 C

SEATING PLANE

1.4MAX

0.45
0.35

⌒ 0.10 C

C
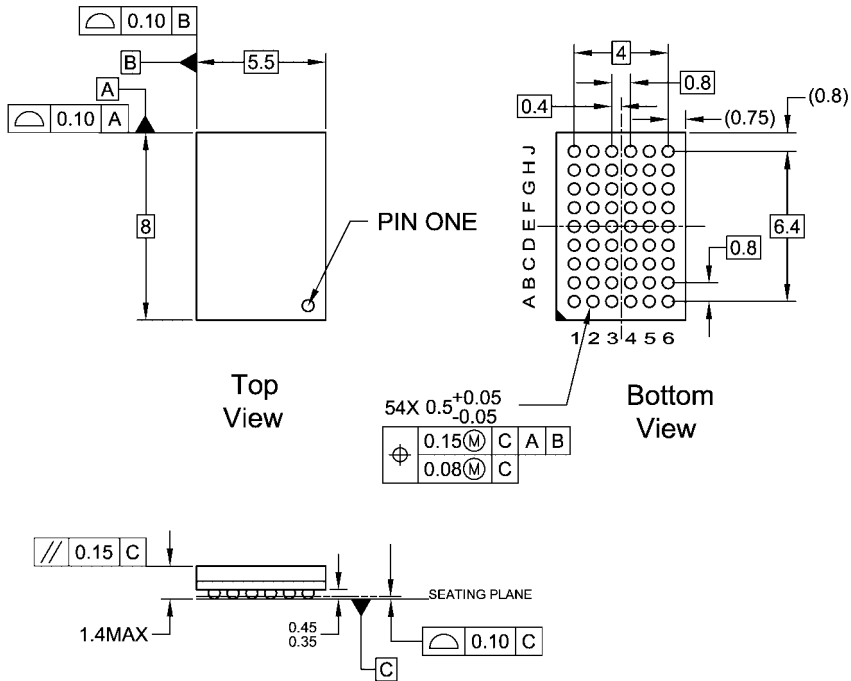
NOTES:
A. THIS PACKAGE CONFORMS TO JEDEC M0-205
B. ALL DIMENSIONS IN MILLIMETERS
C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
   .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
Package Number BGA54A
(Preliminary)

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

LAND PATTERN RECOMMENDATION

DETAIL A
TYPICAL

MTD56 (REV B)
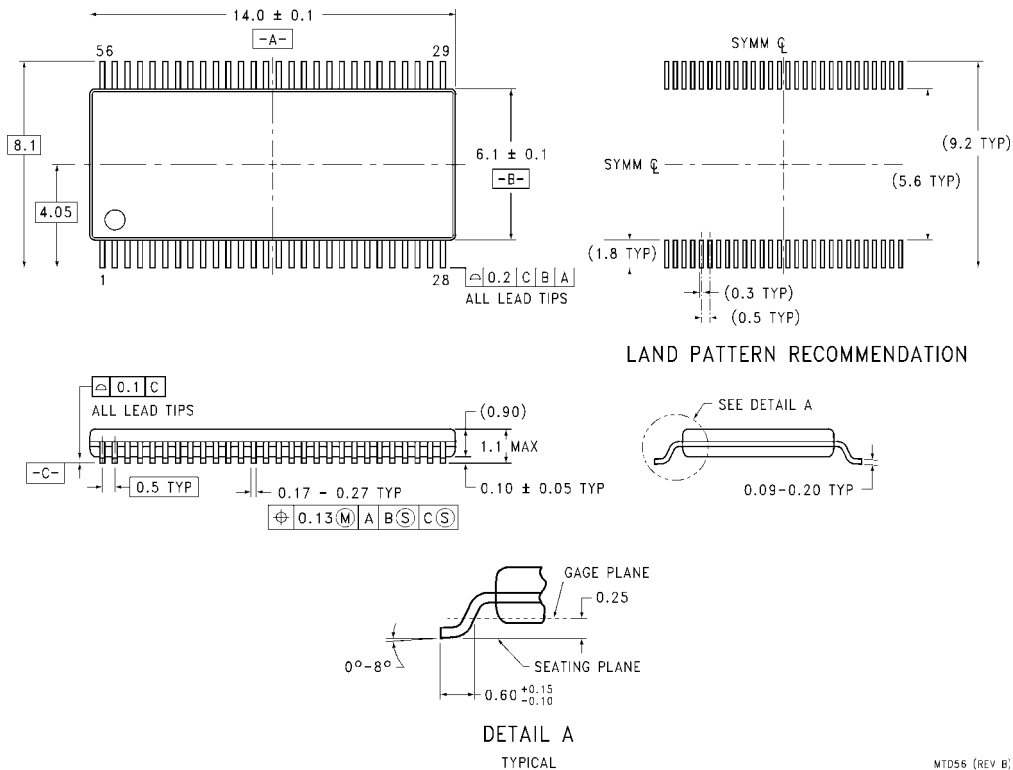
56-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide
Package Number MTD56

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